

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
650V	130mΩ@10V	25A

Feature

- Low on-resistance
- Low gate charge

Application

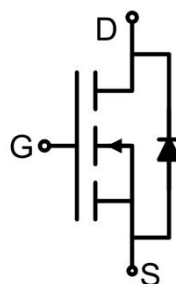
- Power factor correction (PFC)
- Uninterruptible Power Supply (UPS)

Package

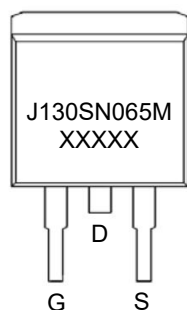


TO-263AB

Circuit diagram



Marking



Absolute Maximum Ratings (T_c=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V _{DS} =0V)	V _{DS}	650	V
Gate-Source Voltage	V _{GS}	±30	V
Continuous Drain Current	I _D	25	A
Pulsed Drain Current ¹⁾	I _{DM}	75	A
Single Pulse Avalanche Energy ²⁾	E _{AS}	750	mJ
Power Dissipation ³⁾	P _D	47	W
Thermal Resistance Junction to Case	R _{θJC}	2.65	°C/W
Operating Junction Temperature	T _J	-55 ~ +150	°C
Storage Temperature	T _{STG}	-55 ~ +150	°C

Electrical characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	650			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =650V, V _{GS} =0V			1	μA
Gate-body leakage current	I _{GSS}	V _{DS} =0V, V _{GS} =±30V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.5	3.5	4.5	V
Drain-source on-resistance	R _{DS(on)}	V _{GS} =10V, I _D =12.5A		100	130	mΩ
Dynamic characteristics ⁴⁾						
Input Capacitance	C _{iss}	V _{DS} =100V, V _{GS} =0V, f =1MHz		2113		pF
Output Capacitance	C _{oss}			92		
Reverse Transfer Capacitance	C _{rss}			1		
Total Gate Charge	Q _g	V _{DS} =325V, V _{GS} =10V, I _D =25A		49.4		nC
Gate-Source Charge	Q _{gs}			10.8		
Gate-Drain Charge	Q _{gd}			18.8		
Turn-on delay time	t _{d(on)}	V _{DS} =325V, V _{GS} =10V, I _D =25A R _G =25Ω		40		nS
Turn-on rise time	t _r			53		
Turn-off delay time	t _{d(off)}			191		
Turn-off fall time	t _f			41		
Source-Drain Diode characteristics						
Diode Forward Current	I _S				25	A
Diode Forward voltage	V _{SD}	V _{GS} =0V, I _S =25A			1.3	V
Reverse Recovery Time	T _{rr}	V _{GS} =0V, I _F =25A di/dt =100A/μs		331		nS
Reverse Recovery Charge	Q _{rr}			5.3		μC

Notes:

- 1) The data tested by surface mounted on a 1 inch2 FR-4 board with 20Z copper.
- 2) The EAS data shows Max. rating : L=60mH, I_{AS} = 5A, V_{DD} = 50V, R_G=25Ω. Starting at T_J = 25°C.
- 3) The power dissipation is limited by 150°C junction temperature.
- 4) Guaranteed by design, not subject to production testing.

Typical Characteristics

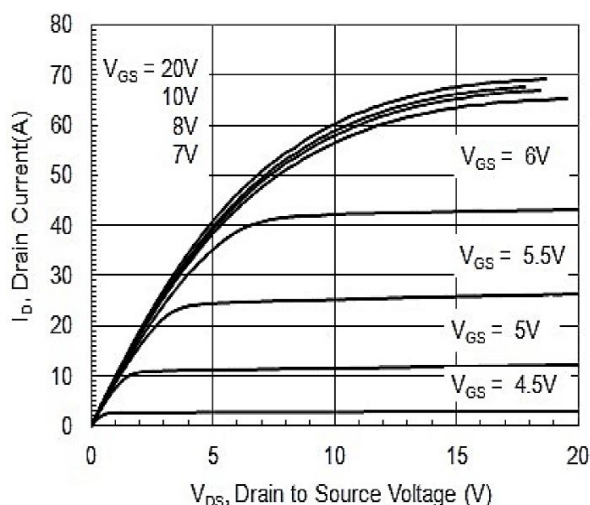


Figure1: Output characteristics

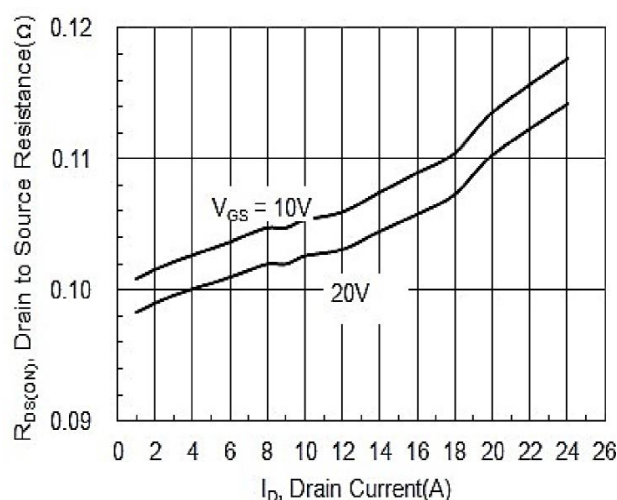


Figure2: Drain source on state resistance

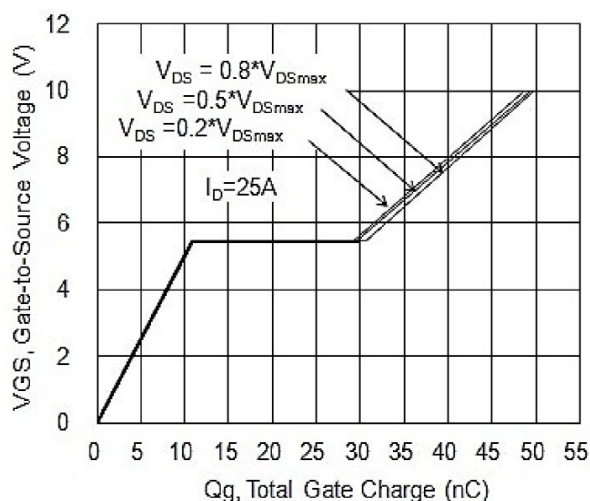


Figure3: Gate charge characteristics

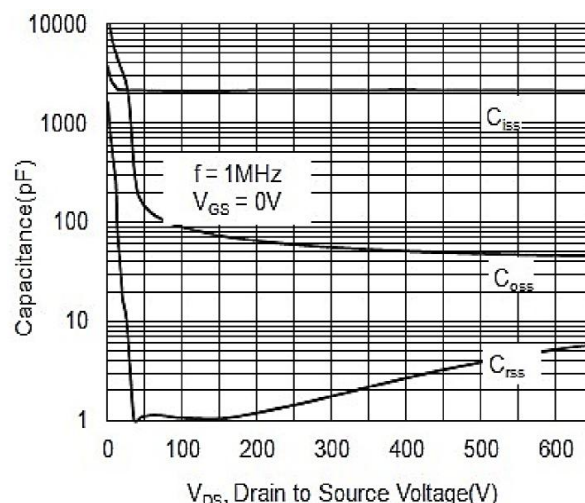


Figure4: Capacitance Characteristics

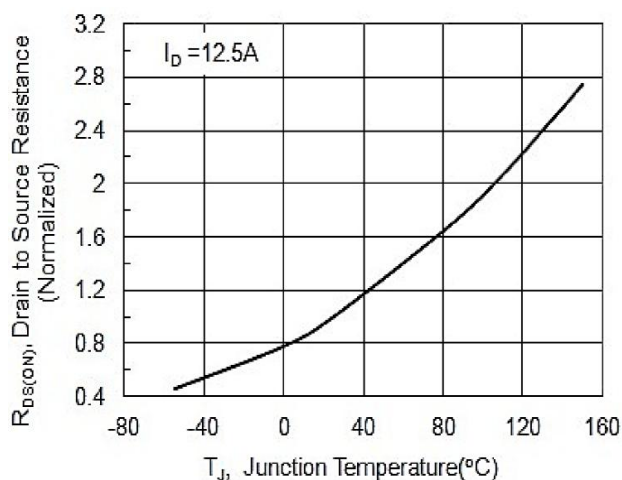


Figure5: Rds (on) Vs junction temperature

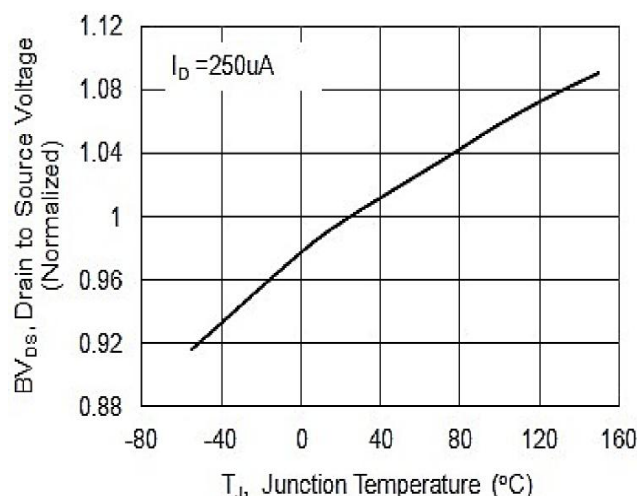


Figure6: BV_{DSS} vs junction temperature

Typical Characteristics

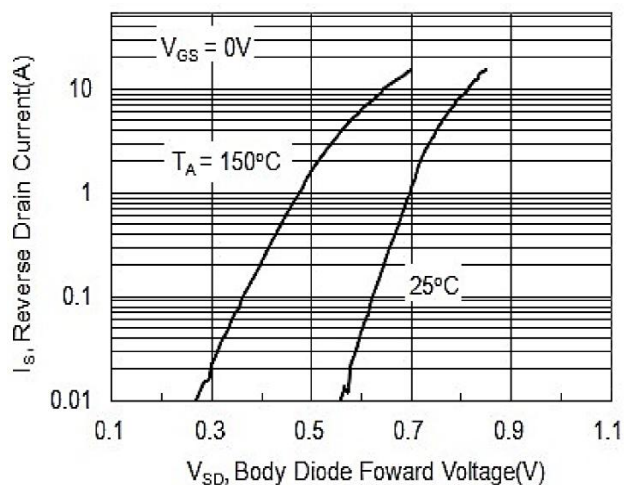


Figure7:VGS (th) vs junction temperature

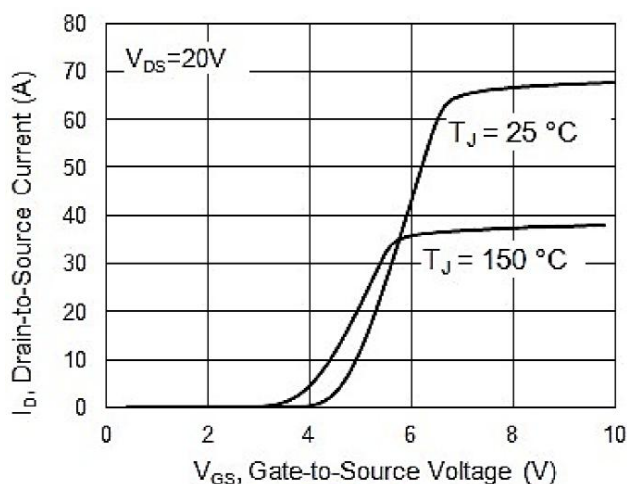


Figure8: Transfer characteristics

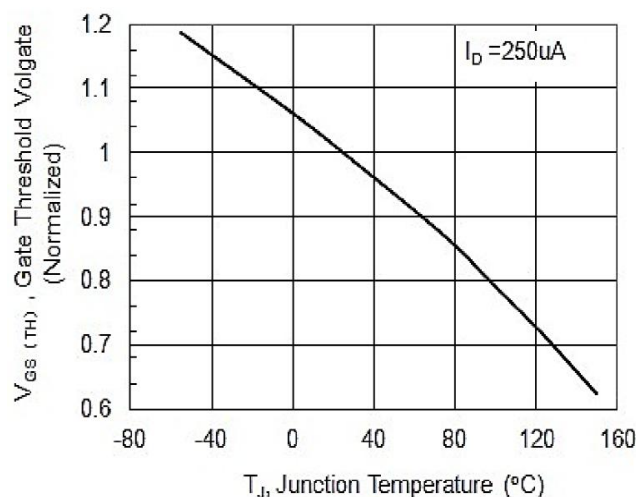


Figure9: VGS (th) vs junction temperature

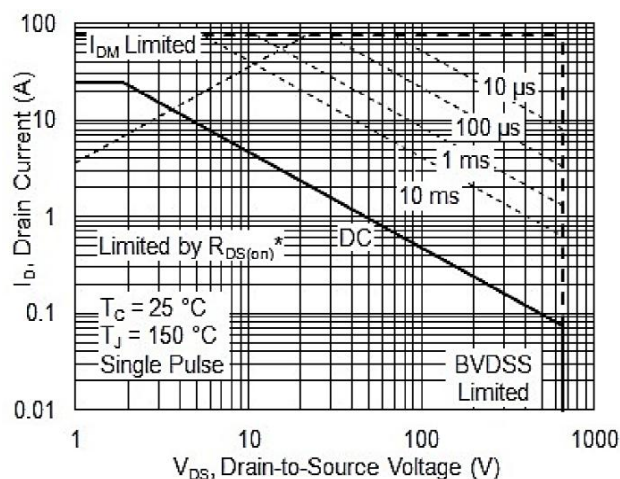


Figure10: Safe operating area

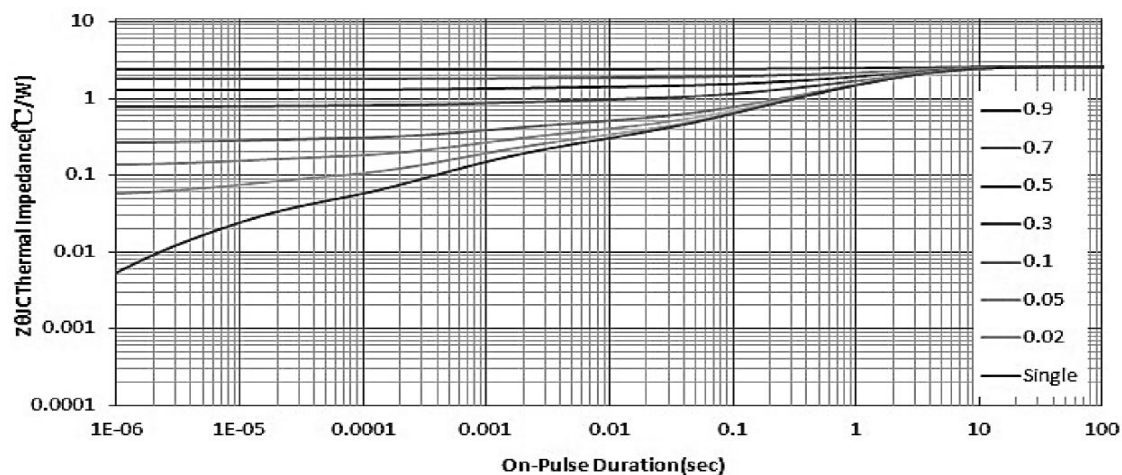
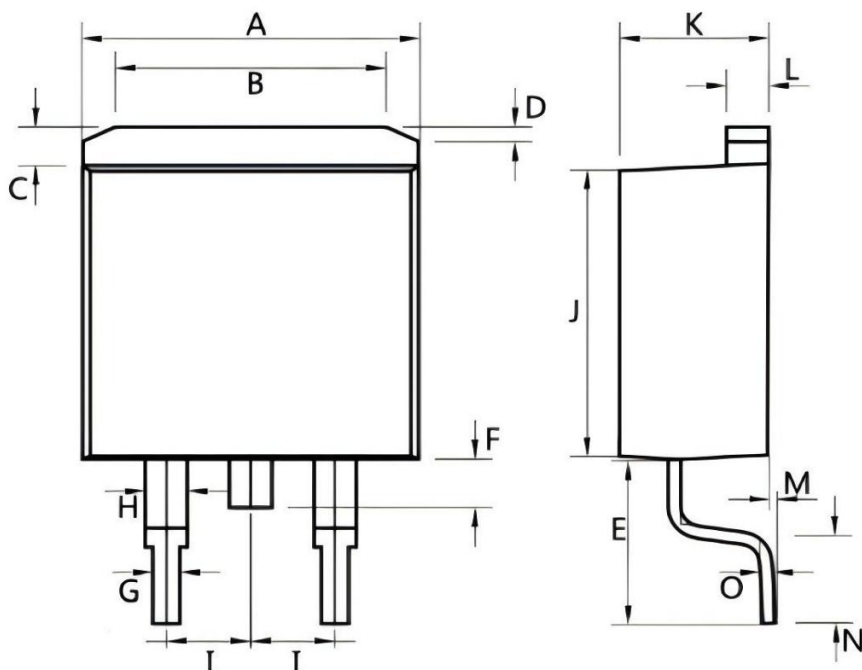


Figure11: Transient thermal impedance

TO-263AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	10.000	10.500	0.394	0.413
B	7.250	7.750	0.285	0.305
C	1.300	1.500	0.051	0.059
D	0.550	0.750	0.022	0.030
E	5.000	6.000	0.197	0.236
F	1.400	1.600	0.055	0.063
G	0.750	0.950	0.030	0.037
H	1.150	1.350	0.045	0.053
I	2.540 TYP.		0.100 TYP.	
J	8.400	8.600	0.331	0.339
K	4.400	4.600	0.173	0.181
L	1.250	1.450	0.049	0.057
M	0.020	0.100	0.001	0.004
N	2.400	2.800	0.094	0.110
O	0.350	0.450	0.014	0.018